

Gate resistor installed Dual N-channel MOSFET

KFCAB21860L Data Sheet

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1. GENERAL DESCRIPTION

Gate resistor installed Dual N-channel MOSFET
For lithium-ion secondary battery protection circuits

2. FEATURES

- Source-source ON resistance: $R_{SS}(\text{on})$ typ. = 1.5 m Ω ($V_{GS} = 3.8$ V)
- CSP (Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1)

3. MARKING SYMBOL: WH

4. PACKAGING

Embossed type (Thermo-compression sealing): 8,000 pcs / reel (standard)

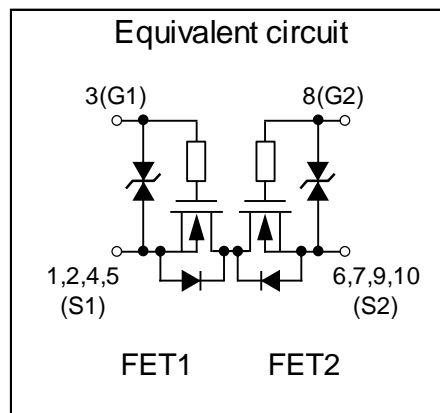
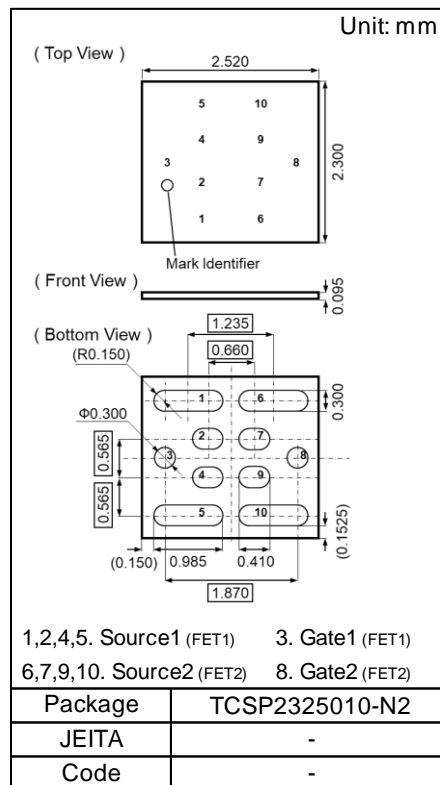
5. ABSOLUTE MAXIMUM RATINGS $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Source-source Voltage	VSS	12	V
Gate-source Voltage	VGS	± 8	V
Source Current	DC	IS1 ^{*1}	A
		IS2 ^{*2}	
		IS3 ^{*3}	
	Pulsed ^{*4}	ISp	170
Total Power Dissipation	DC	PD1 ^{*1}	W
		PD2 ^{*2}	
		PD3 ^{*3}	
Channel Temperature	Tch	150	$^\circ\text{C}$
Storage Temperature Range	Tstg	-55 to +150	$^\circ\text{C}$

6. THERMAL CHARACTERISTICS $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Thermal Resistance (ch-a)	Rth ^{*1}	215	$^\circ\text{C} / \text{W}$
	Rth ^{*2}	71	
	Rth ^{*3}	39	

- Note
- *1 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm)
FR4 board partially covered with copper pad (42 mm² area, 36 μm thickness).
 - *2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board fully covered with copper pad (604 mm² area, 36 μm thickness).
 - *3 Mounted on ceramic board (70 mm x 70 mm x t1.0 mm).
 - *4 $t = 10$ μs , Duty Cycle $\leq 1\%$



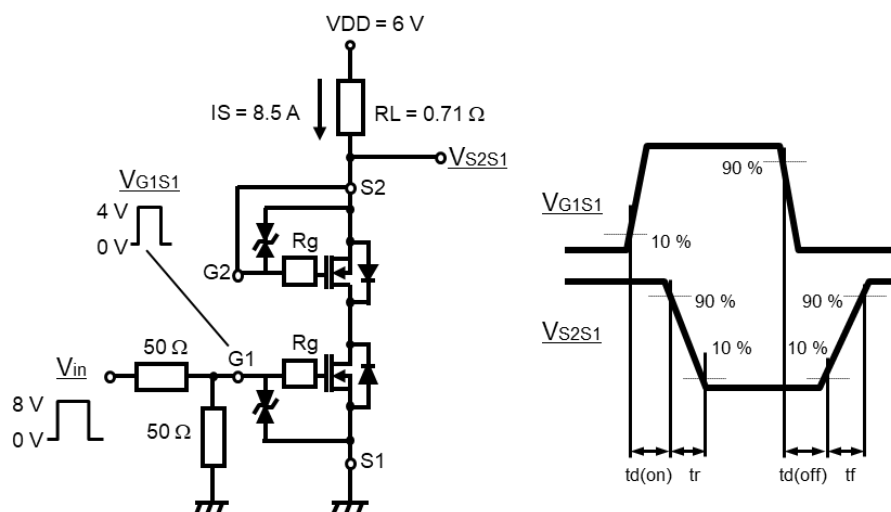
7. ELECTRICAL CHARACTERISTICS $T_a = 25\text{ }^{\circ}\text{C} \pm 3\text{ }^{\circ}\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Source-source Breakdown Voltage	VSSS	$I_S = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	12			V
Zero Gate Voltage Source Current	ISSS	$V_{SS} = 12\text{ V}$, $V_{GS} = 0\text{ V}$			1.0	μA
Gate-source Leakage Current	IGSS1	$V_{GS} = \pm 8\text{ V}$, $V_{SS} = 0\text{ V}$			± 10	μA
	IGSS2	$V_{GS} = \pm 5\text{ V}$, $V_{SS} = 0\text{ V}$			± 1.0	
Gate-source Threshold Voltage	V _{th}	$I_S = 1.04\text{ mA}$, $V_{SS} = 6\text{ V}$	0.35	0.90	1.40	V
Source-source On-state Resistance	RSS(on)1	$I_S = 8.5\text{ A}$, $V_{GS} = 4.5\text{ V}$	1.00	1.35	1.75	m Ω
	RSS(on)2	$I_S = 8.5\text{ A}$, $V_{GS} = 3.8\text{ V}$	1.10	1.50	1.95	
	RSS(on)3	$I_S = 8.5\text{ A}$, $V_{GS} = 3.1\text{ V}$	1.15	1.70	2.80	
	RSS(on)4	$I_S = 8.5\text{ A}$, $V_{GS} = 2.75\text{ V}$	1.20	1.95	3.80	
	RSS(on)5	$I_S = 8.5\text{ A}$, $V_{GS} = 2.5\text{ V}$	1.40	2.25	4.50	
Body Diode Forward Voltage	V _{F(s-s)}	$I_F = 8.5\text{ A}$, $V_{GS} = 0\text{ V}$		0.7	1.0	V
Input Capacitance *1	C _{iss}	$V_{SS} = 10\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ kHz}$		5390		pF
Output Capacitance *1	C _{oss}			890		
Reverse Transfer Capacitance *1	C _{rss}			770		
Turn-on Delay Time *1,*2	t _{d(on)}	$V_{DD} = 6\text{ V}$, $V_{GS} = 0\text{ to }4\text{ V}$ $I_S = 8.5\text{ A}$		1.6		μs
Rise Time *1,*2	t _r			2.6		
Turn-off Delay Time *1,*2	t _{d(off)}	$V_{DD} = 6\text{ V}$, $V_{GS} = 4\text{ to }0\text{ V}$ $I_S = 8.5\text{ A}$		7.5		μs
Fall Time *1,*2	t _f			4.0		
Total Gate Charge *1	Q _g	$V_{DD} = 6\text{ V}$ $V_{GS} = 0\text{ to }4\text{ V}$ $I_S = 17\text{ A}$		45		nC
Gate-source Charge *1	Q _{gs}			12		
Gate-drain Charge *1	Q _{gd}			9		

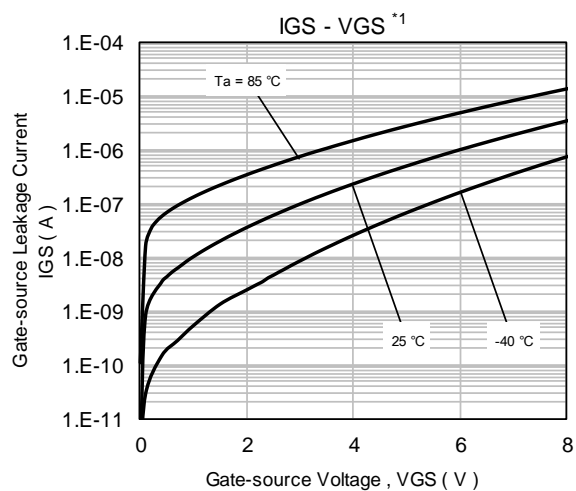
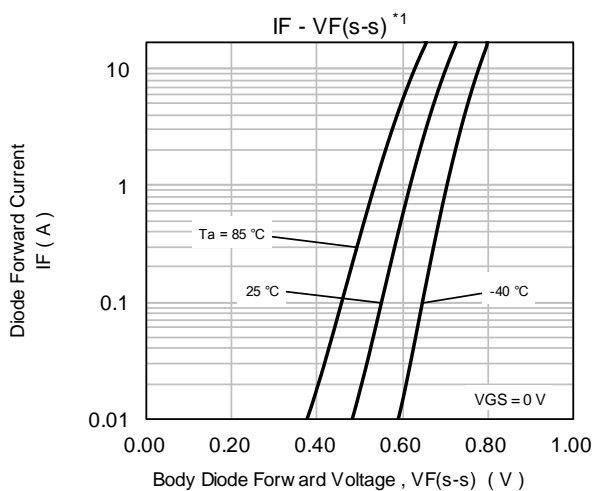
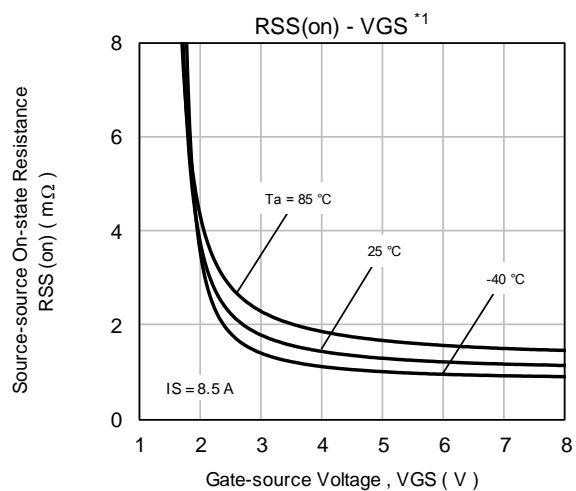
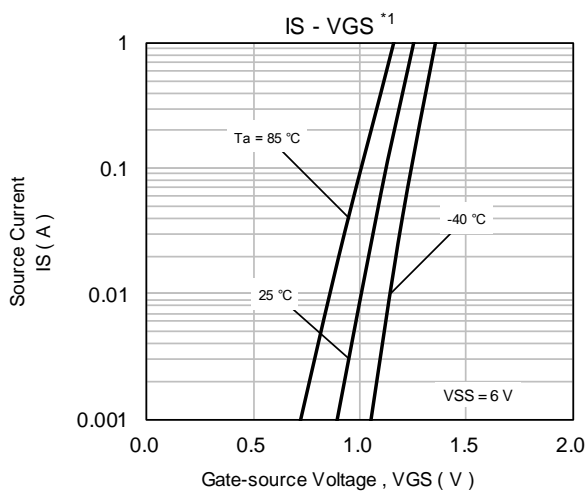
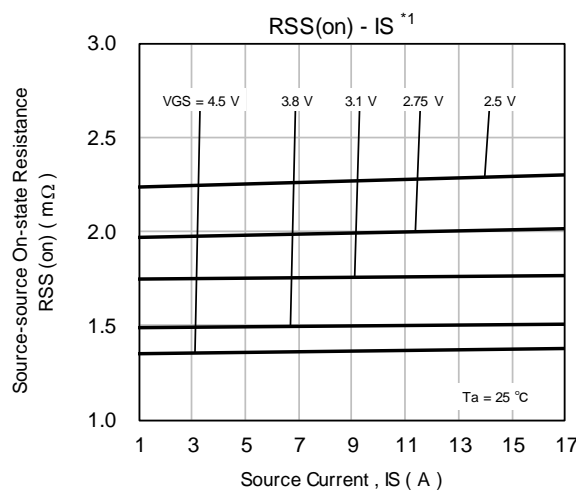
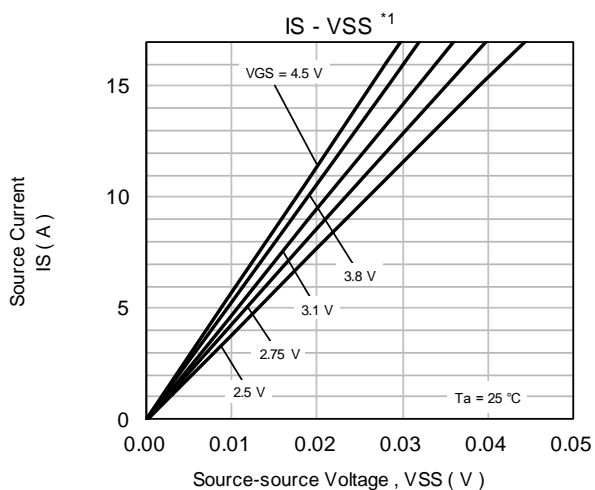
Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

*1 Guaranteed by design, not subject to production testing

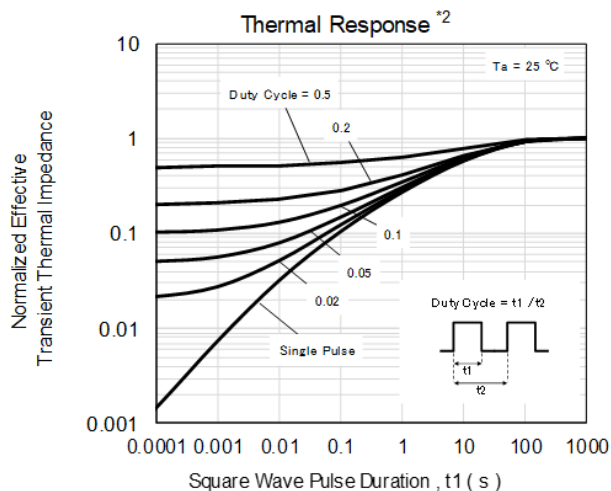
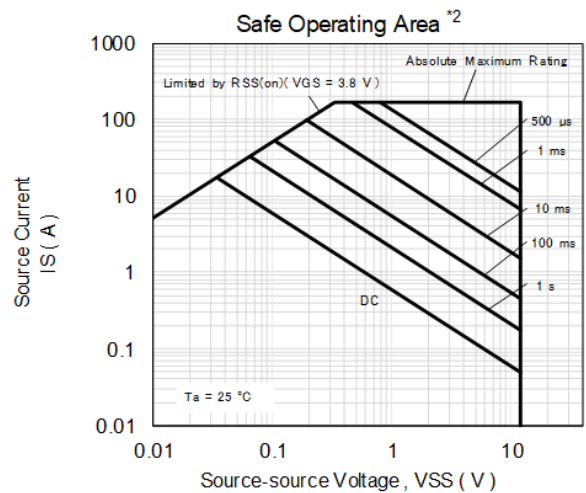
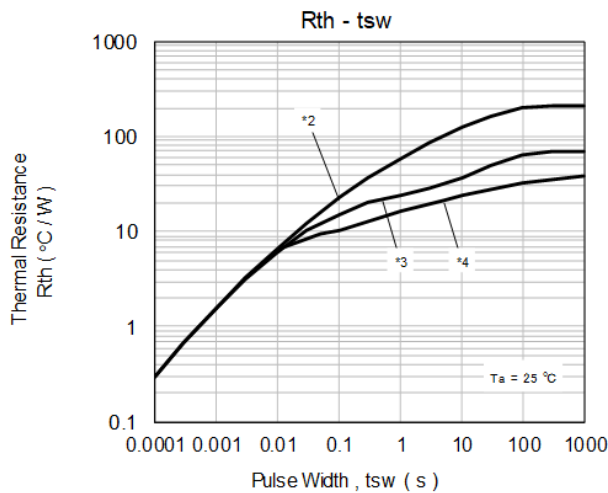
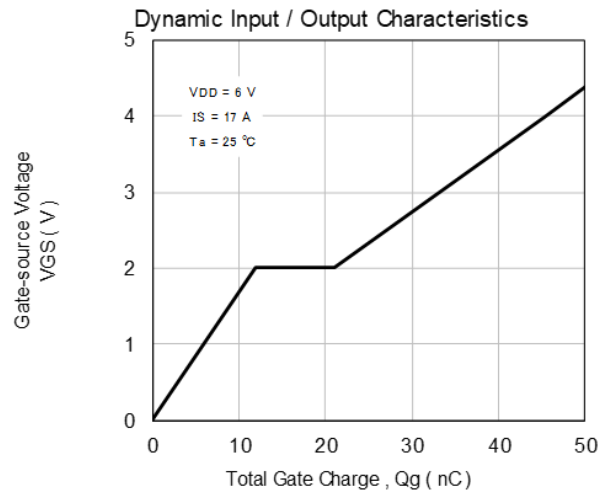
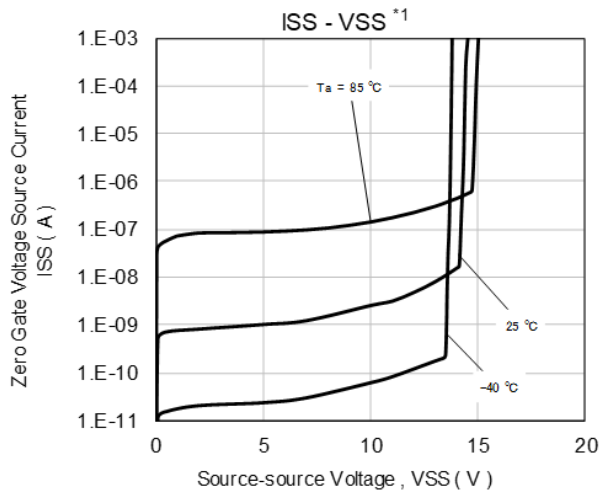
*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time



8. TECHNICAL DATA (Reference)



TECHNICAL DATA (Reference)



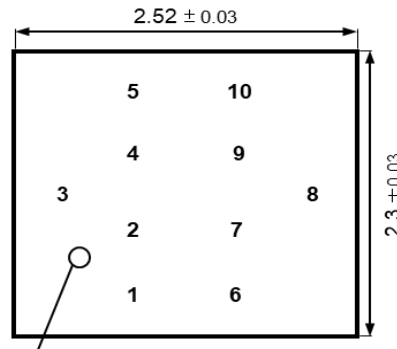
Note

- *1 Pulse measurement.
- *2 Mounted on FR4 board (25.4 mm × 25.4 mm × t1.0 mm).
FR4 board partially covered with copper pad
(42 mm² area, 36 μ m thickness).
- *3 Mounted on FR4 board (25.4 mm × 25.4 mm × t1.0 mm).
FR4 board fully covered with copper pad
(604 mm² area, 36 μ m thickness).
- *4 Mounted on ceramic board (70 mm × 70 mm × t1.0 mm).

9. OUTLINE

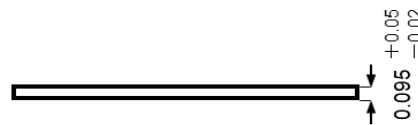
Unit : mm

(Top View)

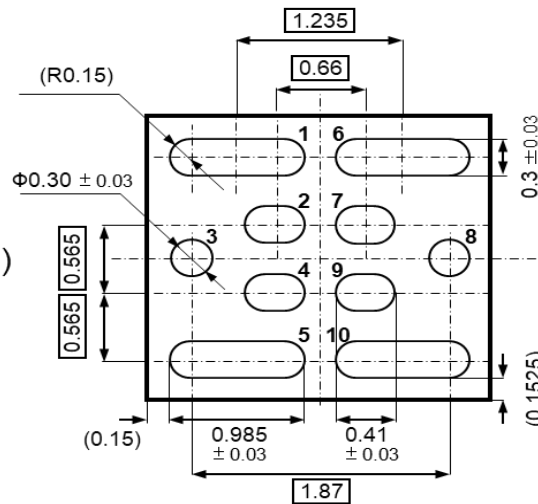


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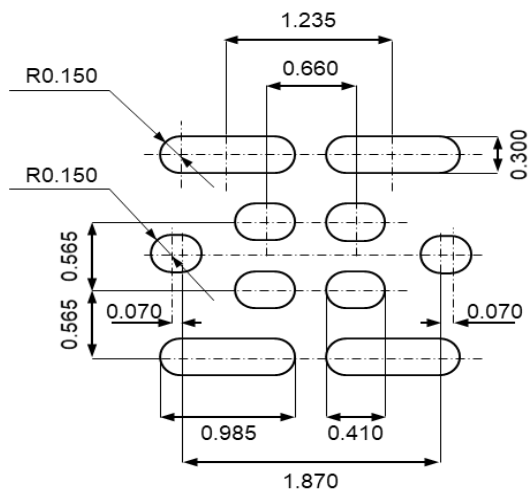
(Front View)



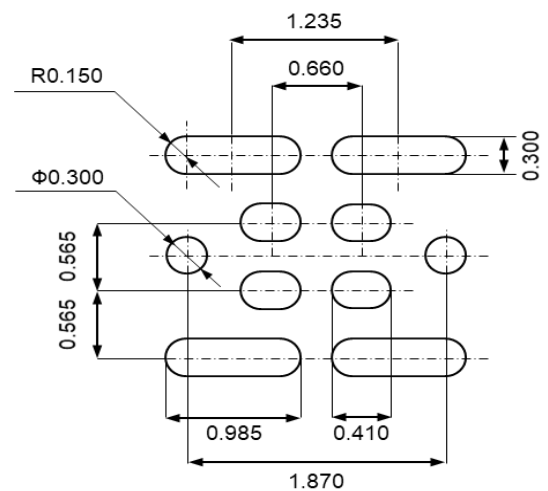
(Bottom View)



10. LAND PATTERN (Reference) Unit: mm



11. STENCIL PATTERN (Reference) Unit: mm



12. REVISION HISTORY

Date	Revision	Description
2021.2.3	1.00	1. initially issued.

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